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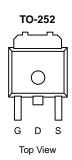
N-Channel 100-V (D-S) MOSFET

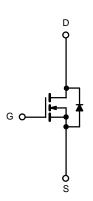
PRODUCT SUMMARY			
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)	
100	0.033 at V _{GS} = 10 V	40	
100	0.043 at V _{GS} = 4.5 V	37.5	

FEATURES

- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 25 ^{\circ}C$, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20	7	
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	I-	40		
	T _C = 125 °C	l _D	23	A	
Pulsed Drain Current		I _{DM}	122	7	
Avalanche Current		I _{AR}	37		
Repetitive Avalanche Energy ^a L = 0.1 mH		E _{AR}	66	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	В	109 ^b	14/	
	T _A = 25 °C ^c	P_{D}	3.92	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	(PCB Mount) ^c	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	1.3	- C/VV	

Notes:

- a. Duty cycle ≤ 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

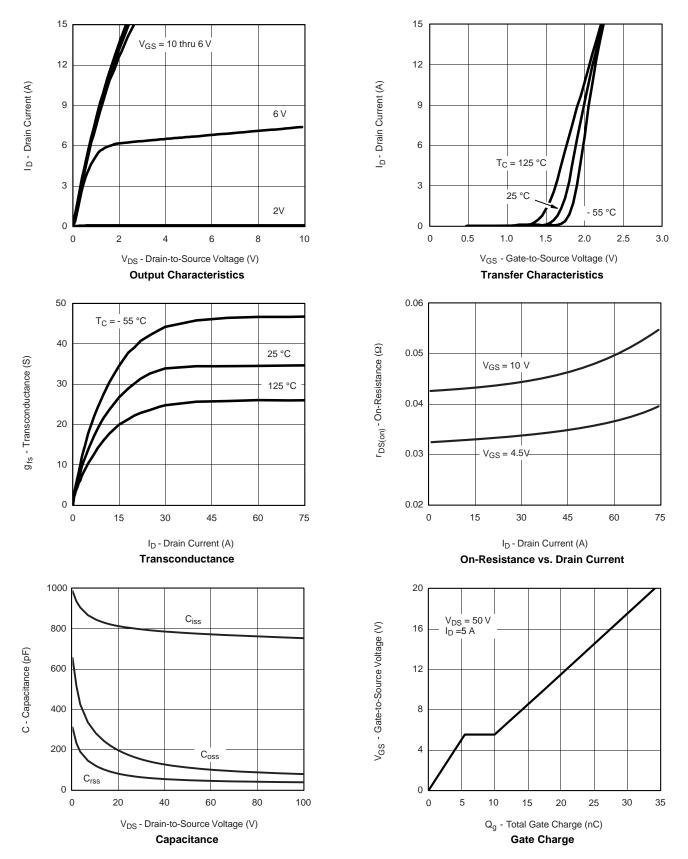


Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{SS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.8		1.8	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$			1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α
Drain-Source On-State Resistance ^a	r	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.033	0.040	Ω
	r _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$		0.043	0.055	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A	20			S
Dynamic ^b						
Input Capacitance	C _{iss}			855		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$		106		
Reverse Transfer Capacitance	C _{rss}			52		
Total Gate Charge ^c	Qg			28	40	nC
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		11		
Gate-Drain Charge ^c	Q_{gd}			9		
Gate Resistance	R_{G}			1.7		Ω
Turn-On Delay Time ^c	t _{d(on)}			17		
Rise Time ^c	t _r	V_{DD} = 50 V, R_L = 2.5 Ω $I_D \cong$ 5 A, V_{GEN} = 10 V, R_G = 2.5 Ω		12		ns
Turn-Off Delay Time ^c	t _{d(off)}			30		
Fall Time ^c	t _f			12		
Source-Drain Diode Ratings and Cha	aracteristics 7	_C = 25 °C ^b				
Continuous Current	I _S			40	^	
Pulsed Current	I _{SM}				125	Α
Forward Voltage ^a	V _{SD}	I _F = 5 A, V _{GS} = 0 V		1.0	1.5	V
Reverse Recovery Time	t _{rr}			67		ns
Peak Reverse Recovery Current	I _{RM(REC)}	$I_F = 5 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		5		Α
Reverse Recovery Charge	Q _{rr}			35		nC

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

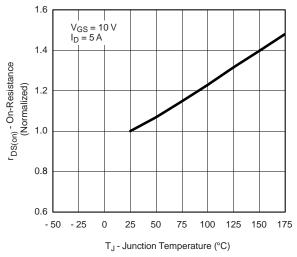
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

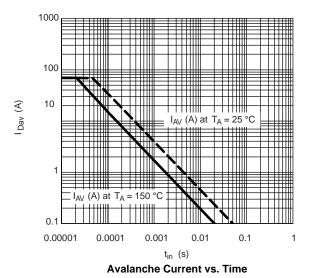


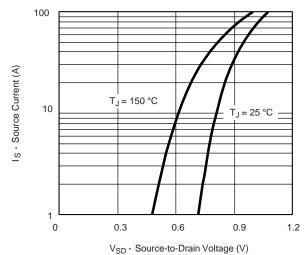


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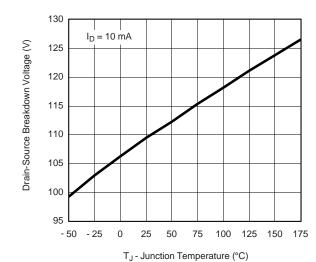


On-Resistance vs. Junction Temperature





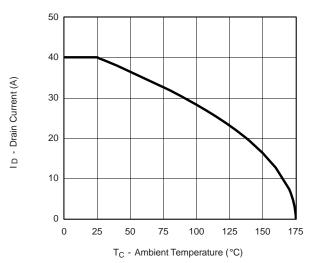
Source-Drain Diode Forward Voltage



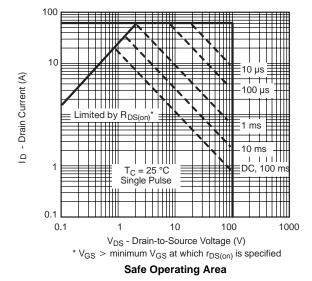
Drain-Source Breakdown Voltage vs. Junction Temperature

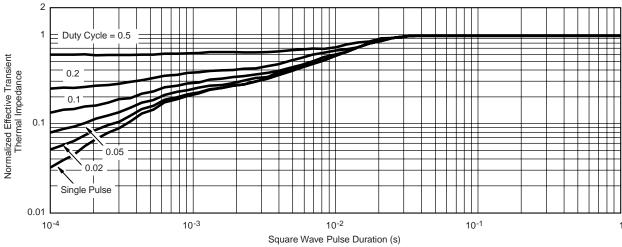


THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature





Normalized Thermal Transient Impedance, Junction-to-Case

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